Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-17 (cancelled).

Claim 18 (currently amended): An apparatus for monitoring plasma process parameters to avoid plasma damage, the apparatus comprising:

a plasma chamber;

a spectrometer for determining optical emissions from the plasma chamber **wherein the spectrometer includes a multiple slit diffraction grating that enables light produced by plasma of the chamber to be split into various spectral components and that are directed onto various associated portions of a sensor array which generates electrical signals that correspond to an optical emission spectrum for the plasma in the chamber**; and

a processor configured to correlate the [[an]] optical emission spectrum with plasma charging values on the wafer.

Claim 19 (original): The apparatus recited in claim 18 wherein the plasma chamber has a viewport for collecting optical emissions.

Claim 20 (original): The apparatus recited in claim 18 further comprising an optical fiber guiding optical emissions from the plasma chamber to the spectrometer.

Claim 21 (cancelled).

Claim 22 (original): The apparatus recited in claim 18 wherein the processor is further configured to adjust the plasma process parameters in response to a

PAGE 4/7 * RCVD AT 3/24/2005 7:18:29 PM [Eastern Standard Time] * SVR:USPTO-EFXRF-1/3 * DNIS:8729306 * CSID:16509618301 * DURATION (mm-ss):02-04

comparison between the measured optical emissions and data correlating optical emissions with plasma charging.

Claim 23 (new): An apparatus for monitoring plasma process parameters to avoid plasma damage, the apparatus comprising:

a plasma chamber;

a spectrometer for determining optical emissions from the plasma chamber wherein the spectrometer includes a rotatable single slit diffraction grating that when rotated enables different spectral frequencies of light produced by plasma of the chamber to be directed onto various associated portions of a sensor array which generates electrical signals that correspond to an optical emission spectrum for the plasma in the chamber; and

a processor configured to correlate the optical emission spectrum with plasma charging values on the wafer.

Claim 24 (new): The apparatus recited in claim 23 wherein the plasma chamber has a viewport for collecting optical emissions.

Claim 25 (new): The apparatus recited in claim 23 further comprising an optical fiber guiding optical emissions from the plasma chamber to the spectrometer.

Claim 26 (new): The apparatus recited in claim 18 wherein the processor is further configured to adjust the plasma process parameters in response to a comparison between the measured optical emissions and data correlating optical emissions with plasma charging.

PAGE 5/7 * RCVD AT 3/24/2005 7:18:29 PM [Eastern Standard Time] * SVR:USPTO-EFXRF-1/3 * DNIS:8729306 * CSID:16509618301 * DURATION (mm-ss):02-04